Dual N-Channel Enhancement Mode MOSFET

Features

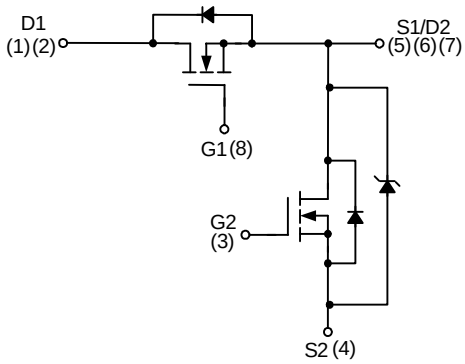
- 30V/7A,
  $R_{DS(ON)}$ =22mΩ (typ.) @ V_{GS} = 10V
  $R_{DS(ON)}$ =26mΩ (typ.) @ V_{GS} = 4.5V
- Super High Dense Cell Design
- Reliable and Rugged
- SOP-8 Package
- Lead Free Available (RoHS Compliant)

Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems

Pin Description

Top View of SOP – 8



N-Channel MOSFET

Ordering and Marking Information

APM4906 □□-□□ □ Lead Free Code Handling Code Temp. Range Package Code	Package Code K : SOP-8 Operating Junction Temp. Range C : -55 to 150 °C Handling Code TU : Tube TR : Tape & Reel Lead Free Code L : Lead Free Device Blank : Original Device
APM4906 K : APM4906 XXXXX	XXXXX - Date Code

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte in plate termination finish; which are fully compliant with RoHS and compatible with both SnPb and lead-free soldering operations. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J STD-020C for MSL classification at lead-free peak reflow temperature.

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter		Rating	Unit
V_{DSS}	Drain-Source Voltage		30	V
V_{GSS}	Gate-Source Voltage		±16	
I_D*	Continuous Drain Current	V_{GS}=10V	7	A
I_{DM}*	Pulsed Drain Current		30	
I_S*	Diode Continuous Forward Current	Channel1	2	A
		Channel2	3	
T_J	Maximum Junction Temperature		150	°C
T_{STG}	Storage Temperature Range		-55 to 150	
P_D*	Maximum Power Dissipation	T_A=25°C	2	W
		T_A=100°C	0.8	
$R_{\theta JA}$*	Thermal Resistance-Junction to Ambient		62.5	°C/W

Note:

*Surface Mounted on 1in^2 pad area, t ≤ 10sec.

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition		APM4906K Min.	APM4906K Typ.	APM4906K Max.	Unit
Static Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA		30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=24V, V_{GS}=0V	Ch1			1	μA
		T_J=85°C	Ch1			30	
		V_{DS}=24V, V_{GS}=0V	Ch2			50	μA
		T_J=85°C	Ch2			5	mA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA		1	1.5	2	V
I_{GSS}	Gate Leakage Current	V_{GS}=±16V, V_{DS}=0V				±100	nA
$R_{DS(ON)}$ [a]	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=7A			22	28	mΩ
		V_{GS}=4.5V, I_{DS}=5A			26	34	
V_{SD} [a]	Diode Forward Voltage	I_{SD}=1A, V_{GS}=0V	Ch1		0.75	1.1	V
			Ch2			0.52	
Gate Charge Characteristics [b]							
Q_g	Total Gate Charge	V_{DS}=15V, V_{GS}=4.5V, I_{DS}=7A			9.5		nC
Q_{gs}	Gate-Source Charge				2.3		
Q_{gd}	Gate-Drain Charge				4.2		

Electrical Characteristics (Cont.) (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition		APM4906K			Unit
				Min.	Typ.	Max.	
Dynamic Characteristics [b]							
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz			2		Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=15V, Frequency=1.0MHz			880		pF
C_{oss}	Output Capacitance		Ch1		130		
			Ch2		160		
C_{rss}	Reverse Transfer Capacitance				90		
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=15V, R_L=15Ω, I_{DS}=1A, V_{GEN}=10V, R_G=6Ω			10		ns
t_r	Turn-on Rise Time				18		
$t_{d(OFF)}$	Turn-off Delay Time				30		
t_f	Turn-off Fall Time				8		

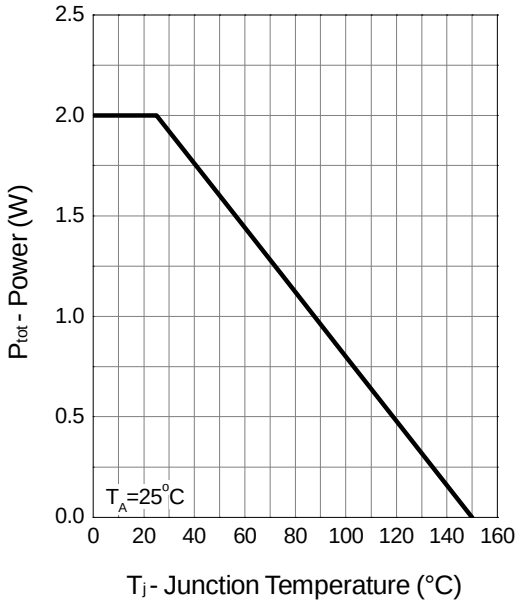
Notes:

a : Pulse test ; pulse width≤300μs, duty cycle≤2%.

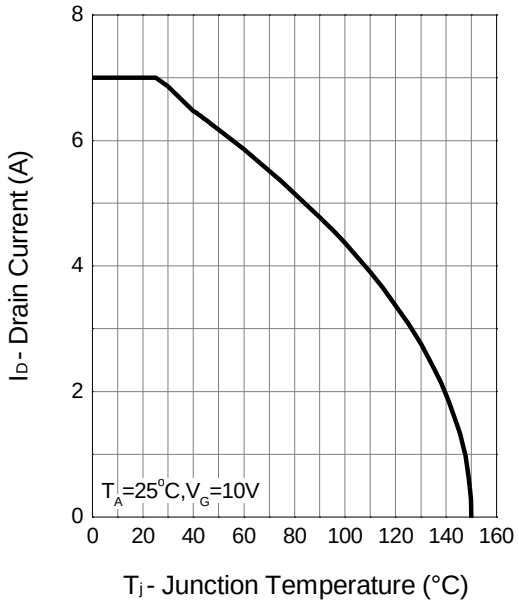
b : Guaranteed by design, not subject to production testing.

Typical Characteristics

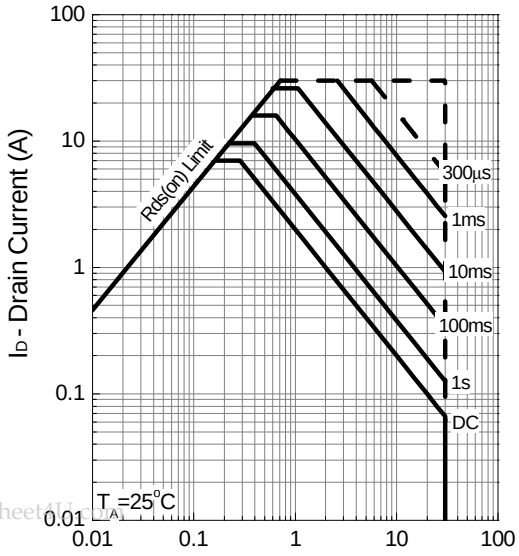
Power Dissipation



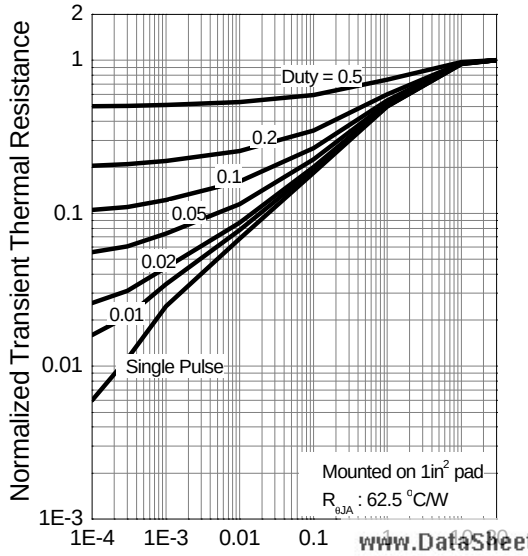
Drain Current



Safe Operation Area

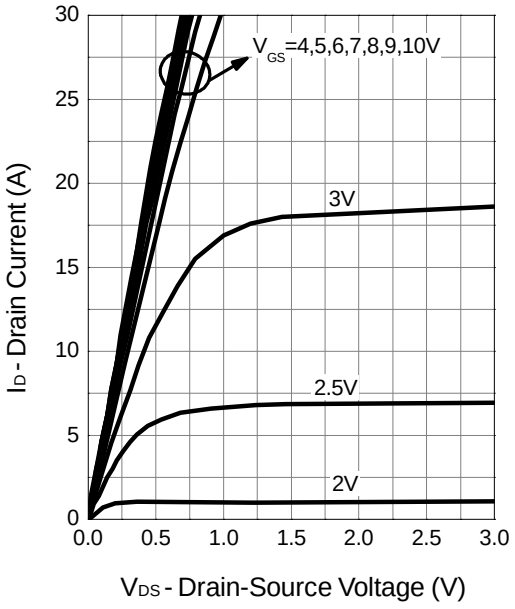


Thermal Transient Impedance

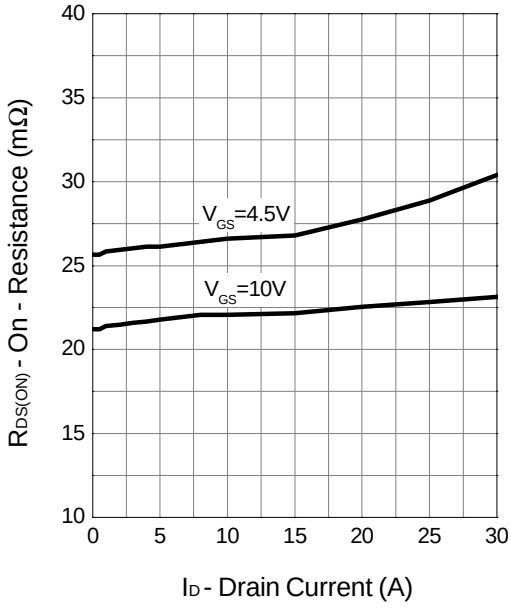


Typical Characteristics (Cont.)

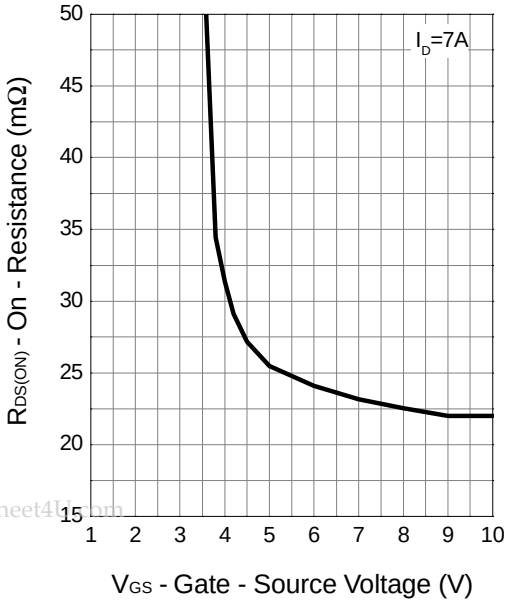
Output Characteristics



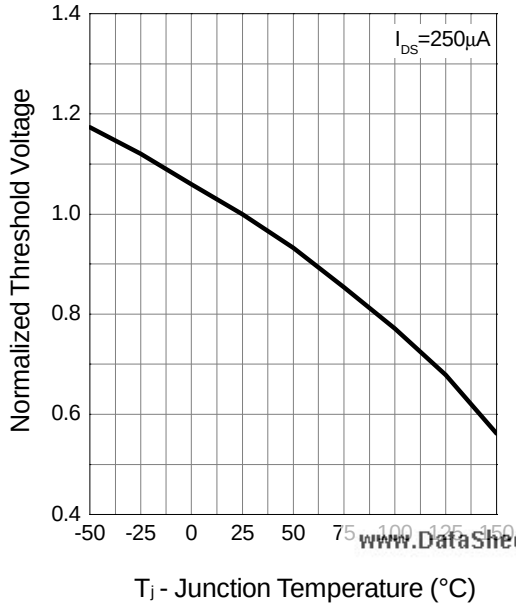
Drain-Source On Resistance



Drain-Source On Resistance

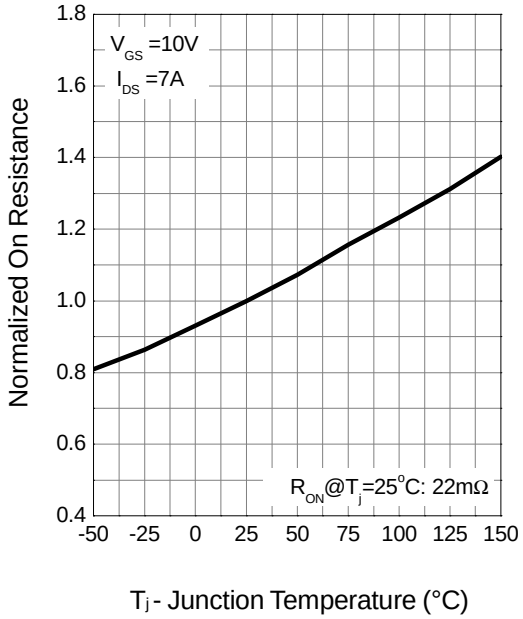


Gate Threshold Voltage

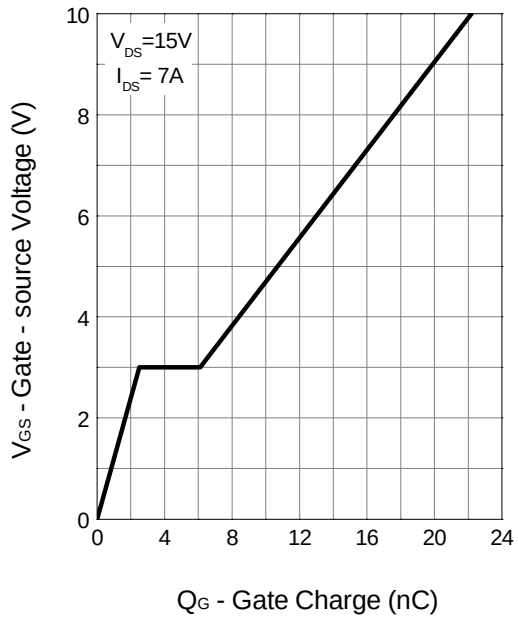


Typical Characteristics (Cont.)

Drain-Source On Resistance

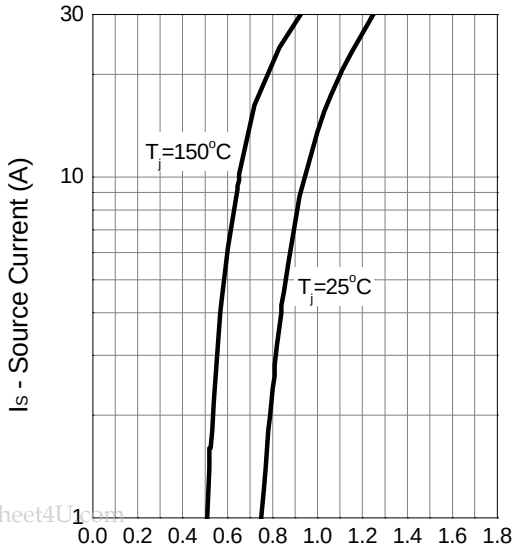


Gate Charge

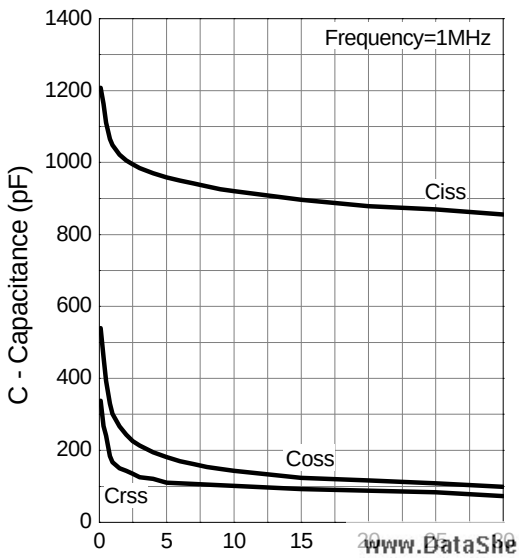


Channel 1

Source-Drain Diode Forward



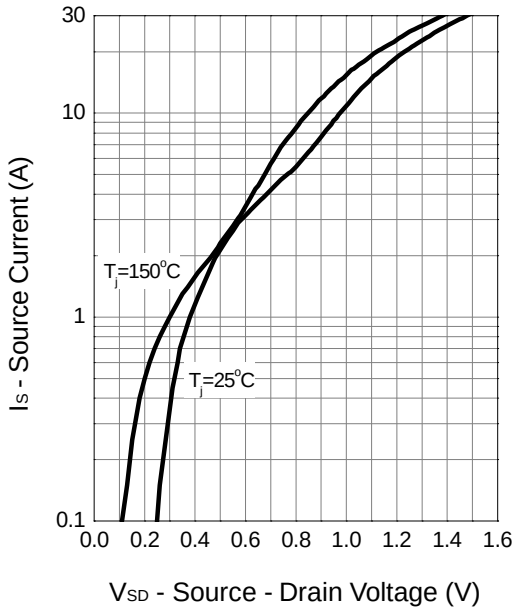
Capacitance



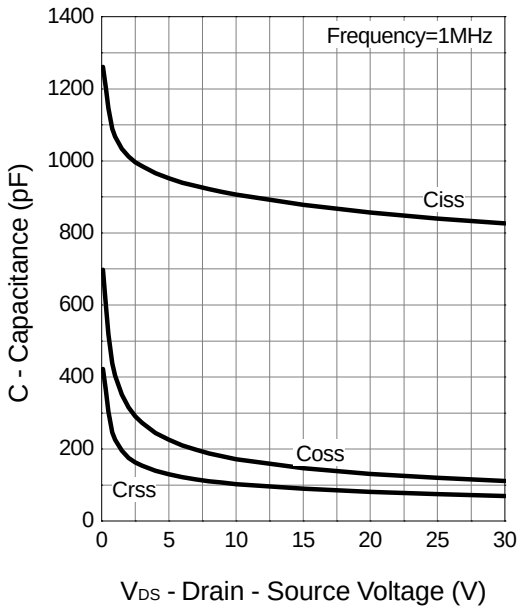
Typical Characteristics (Cont.)

Channel 2

Source-Drain Diode Forward

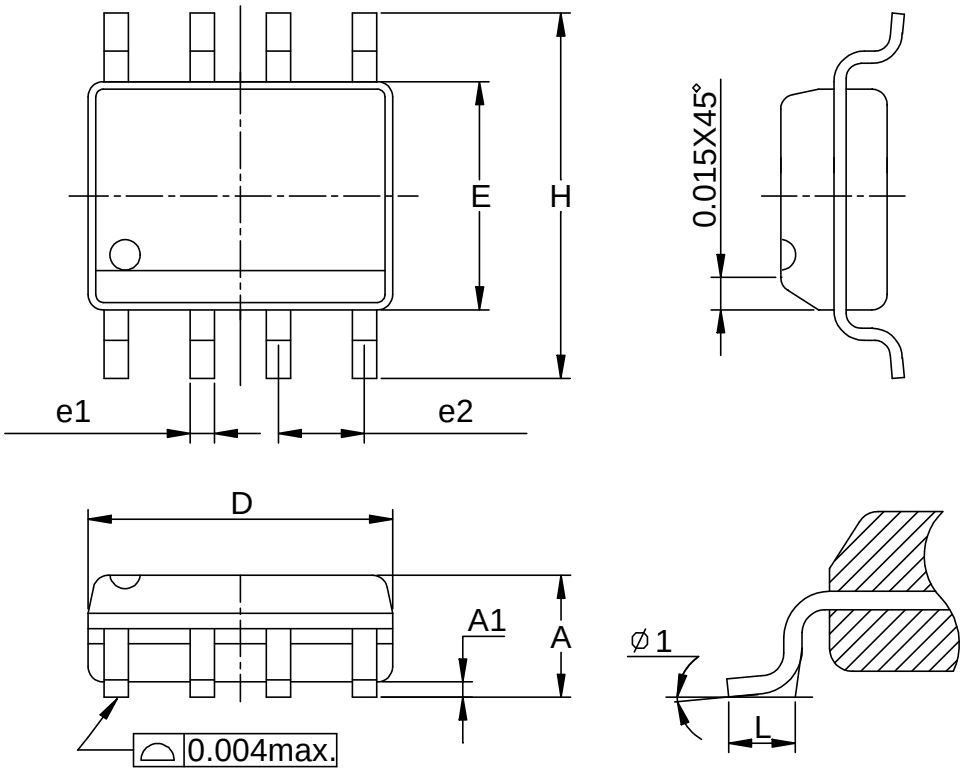


Capacitance



Packaging Information

SOP-8 pin (Reference JEDEC Registration MS-012)

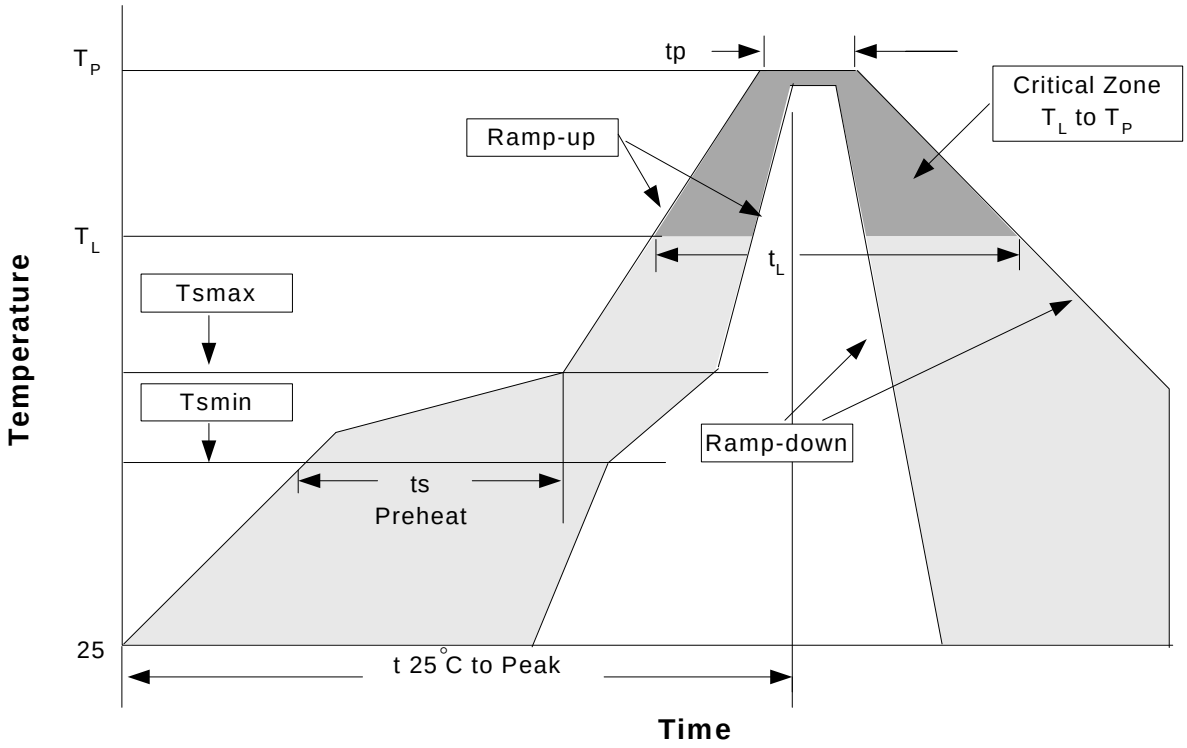


Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.35	1.75	0.053	0.069
A1	0.10	0.25	0.004	0.010
D	4.80	5.00	0.189	0.197
E	3.80	4.00	0.150	0.157
H	5.80	6.20	0.228	0.244
L	0.40	1.27	0.016	0.050
e1	0.33	0.51	0.013	0.020
e2	1.27BSC		0.50BSC	
ϕ1	8°		8°	

Physical Specifications

Terminal Material	Solder-Plated Copper (Solder Material : 90/10 or 63/37 SnPb), 100%Sn
Lead Solderability	Meets EIA Specification RSI86-91, ANSI/J-STD-002 Category 3.

Reflow Condition (IR/Convection or VPR Reflow)



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.	3°C/second max.
Preheat - Temperature Min (Tsmin) - Temperature Max (Tsmax) - Time (min to max) (ts)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak/Classificatioon Temperature (Tp)	See table 1	See table 2
Time within 5°C of actual Peak Temperature (tp)	10-30 seconds	20-40 seconds
Ramp-down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Notes: All temperatures refer to topside of the package .Measured on the body surface.

Classification Reflow Profiles(Cont.)

Table 1. SnPb Entectic Process – Package Peak Reflow Temperatures

Package Thickness	Volume mm^3 <350	Volume mm^3 ³350
<2.5 mm	240 +0/-5°C	225 +0/-5°C
≥2.5 mm	225 +0/-5°C	225 +0/-5°C

Table 2. Pb-free Process – Package Classification Reflow Temperatures

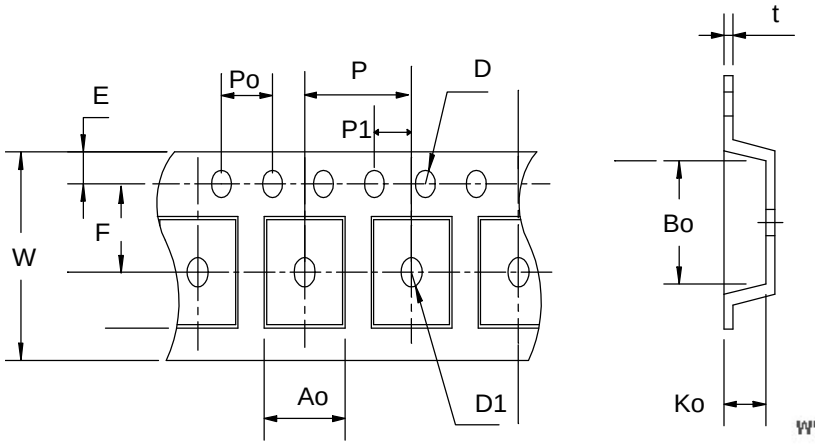
Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
<1.6 mm	260 +0°C*	260 +0°C*	260 +0°C*
1.6 mm – 2.5 mm	260 +0°C*	250 +0°C*	245 +0°C*
≥2.5 mm	250 +0°C*	245 +0°C*	245 +0°C*

*Tolerance: The device manufacturer/supplier **shall** assure process compatibility up to and including the stated classification temperature (this means Peak reflow temperature +0°C. For example 260°C+0°C) at the rated MSL level.

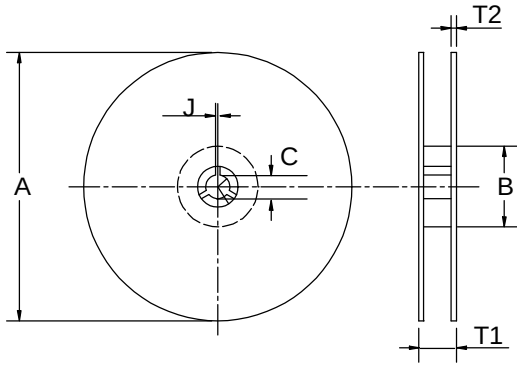
Reliability Test Program

Test item	Method	Description
SOLDERABILITY	MIL-STD-883D-2003	245°C,5 SEC
HOLT	MIL-STD 883D-1005.7	1000 Hrs Bias @ 125°C
PCT	JESD-22-B, A102	168 Hrs, 100% RH, 121°C
TST	MIL-STD 883D-1011.9	-65°C ~ 150°C, 200 Cycles

Carrier Tape & Reel Dimensions



Carrier Tape & Reel Dimensions(Cont.)



Application	A	B	C	J	T1	T2	W	P	E
SOP-8	330±1	62 ± 1.5	12.75 + 0.1 5	2 + 0.5	12.4 +0.2	2± 0.2	12 + 0.3 - 0.1	8± 0.1	1.75± 0.1
	F	D	D1	Po	P1	Ao	Bo	Ko	t
	5.5 ± 0.1	1.55±0.1	1.55+ 0.25	4.0 ± 0.1	2.0 ± 0.1	6.4 ± 0.1	5.2± 0.1	2.1± 0.1	0.3±0.013

(mm)

Cover Tape Dimensions

Application	Carrier Width	Cover Tape Width	Devices Per Reel
SOP- 8	12	9.3	2500

Customer Service

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